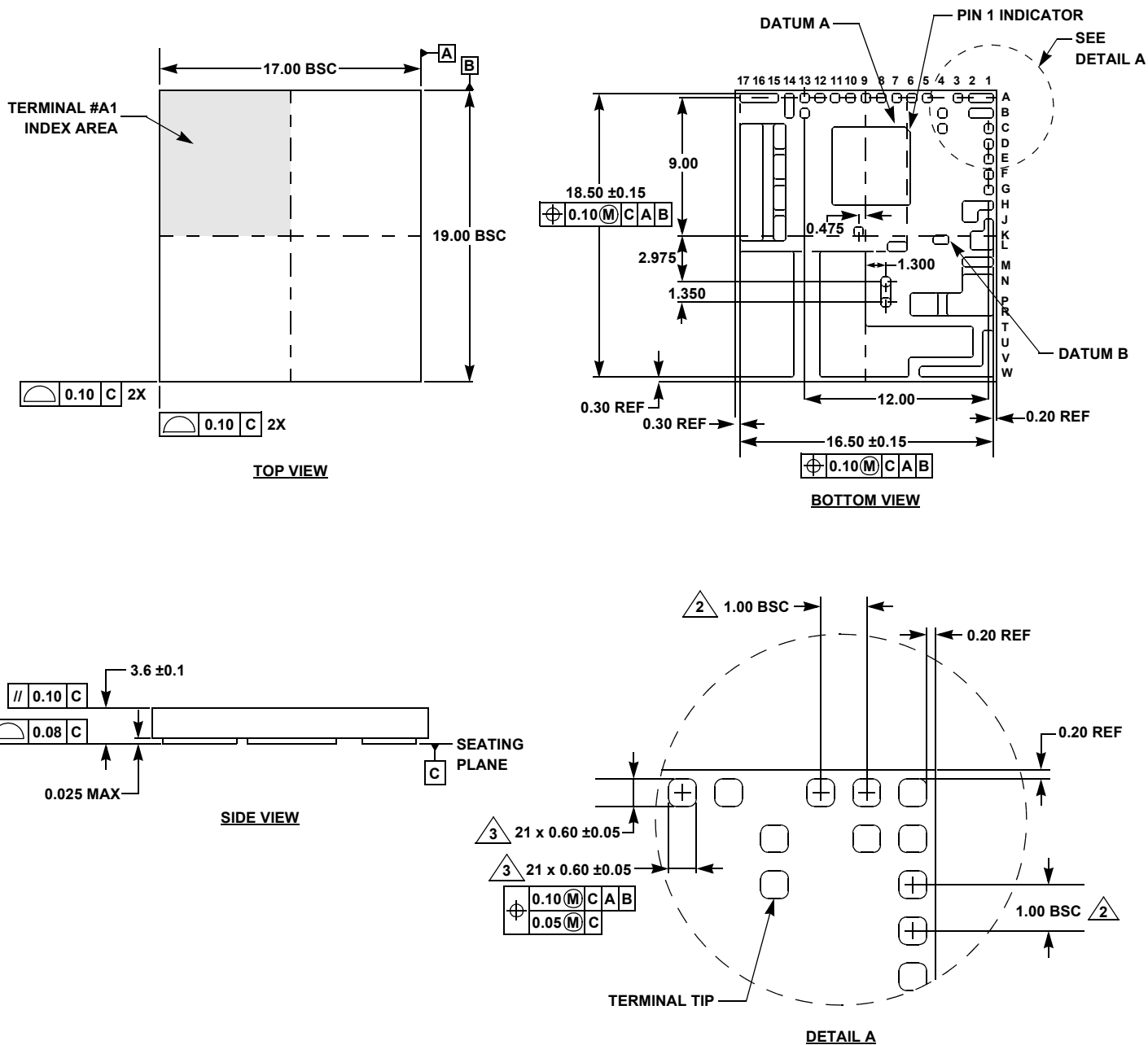


## Package Outline Drawing

**Y41.17x19**

41 I/O 17.0mm x 19.0mmx3.6mm HDA MODULE

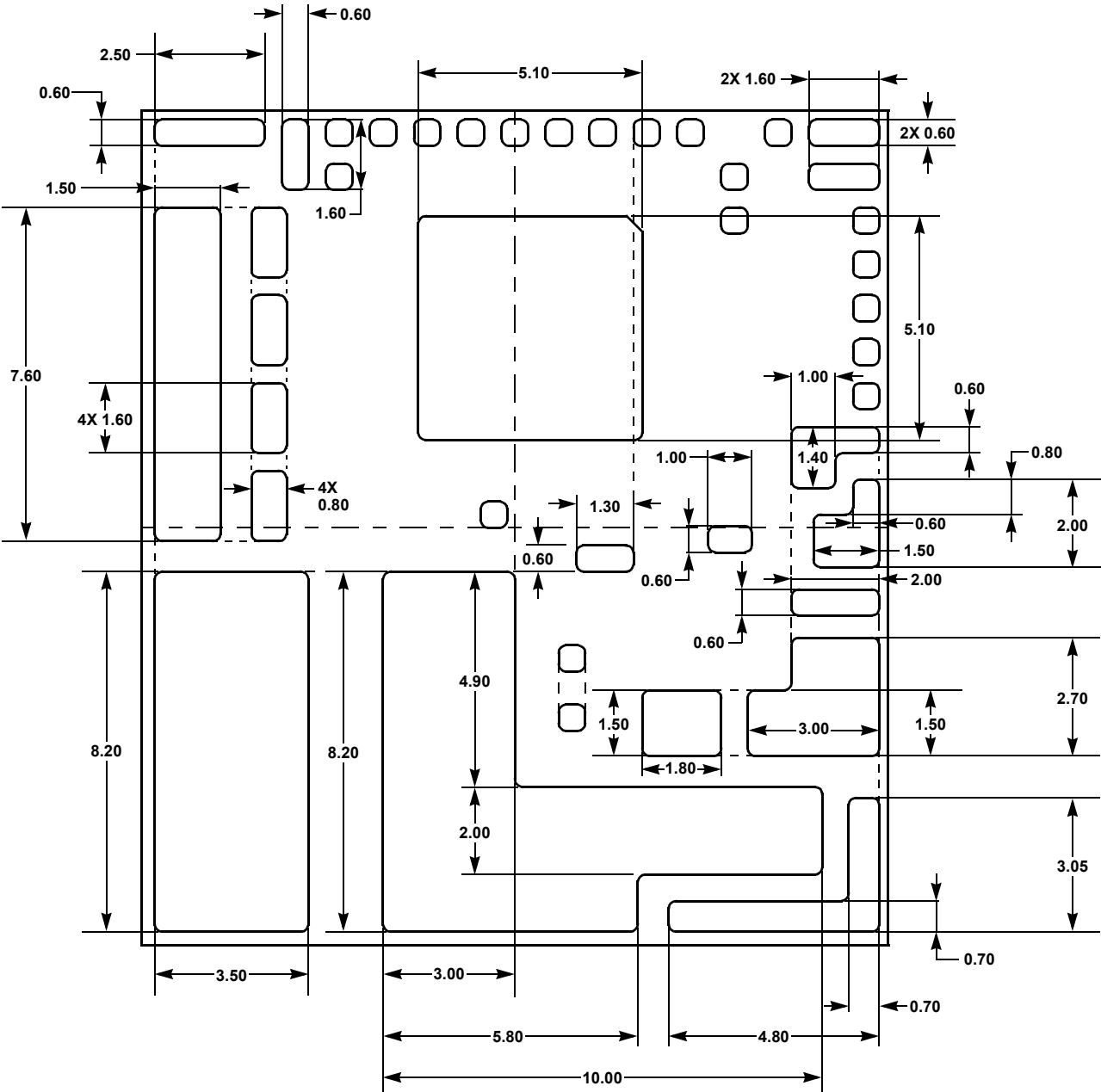
Rev 1, 5/16



**NOTES:**

1. All dimensions are in millimeters.
2. Represents the basic land grid pitch.
3. The total number of I/O (excluding dummy pads).
4. Unless otherwise specified, tolerance: decimal ±0.10.
5. Dimensioning and tolerancing per ASME Y14.M-2009.
6. The configuration of the pin #1 identifier is optional, but must be located within the zone indicated. The pin #1 identifier may be either a mold or mark feature.

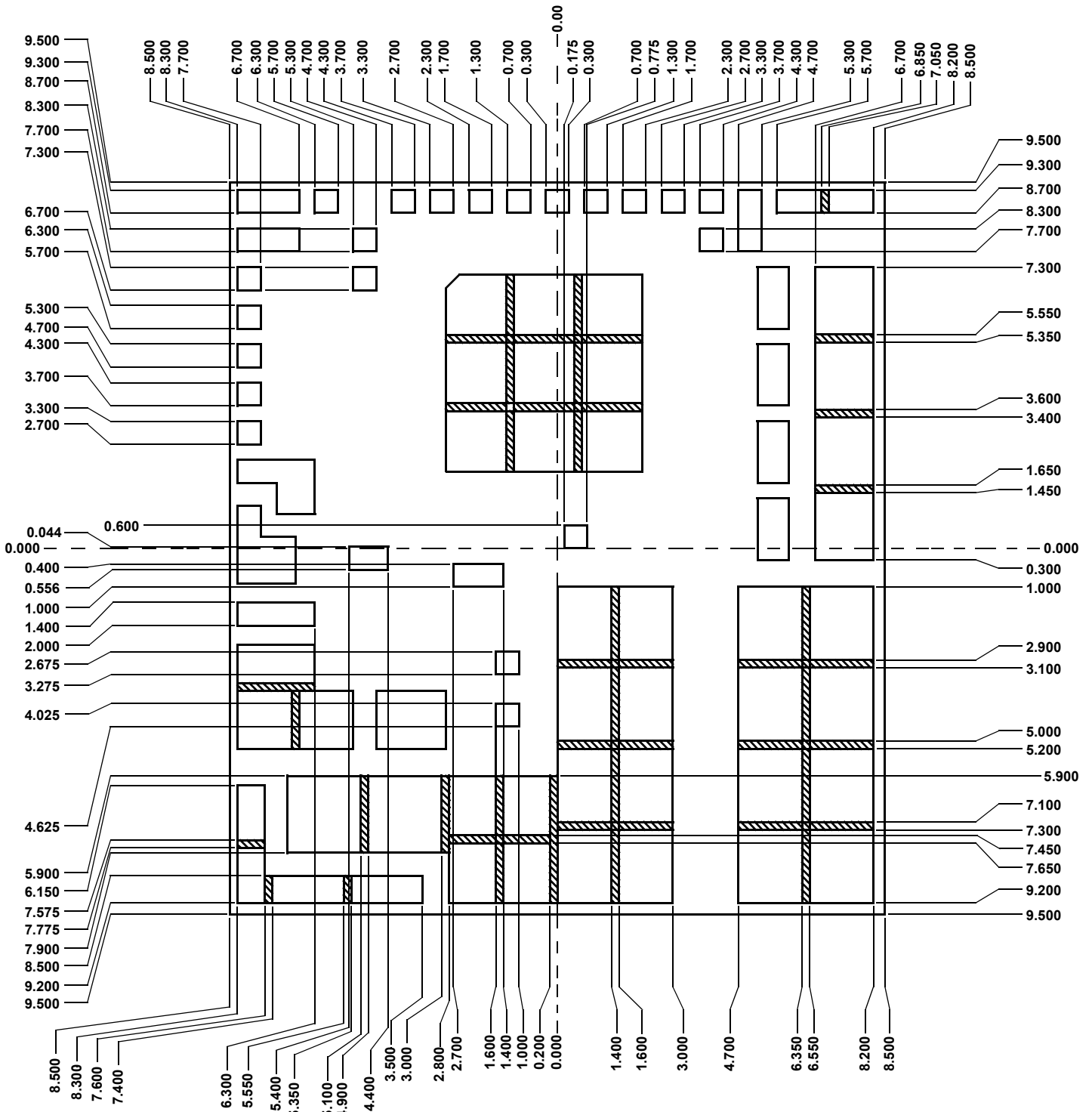
# Plastic Packages for Integrated Circuits



**SIZE DETAILS FOR THE 16 EXPOSED DAPS  
BOTTOM VIEW**

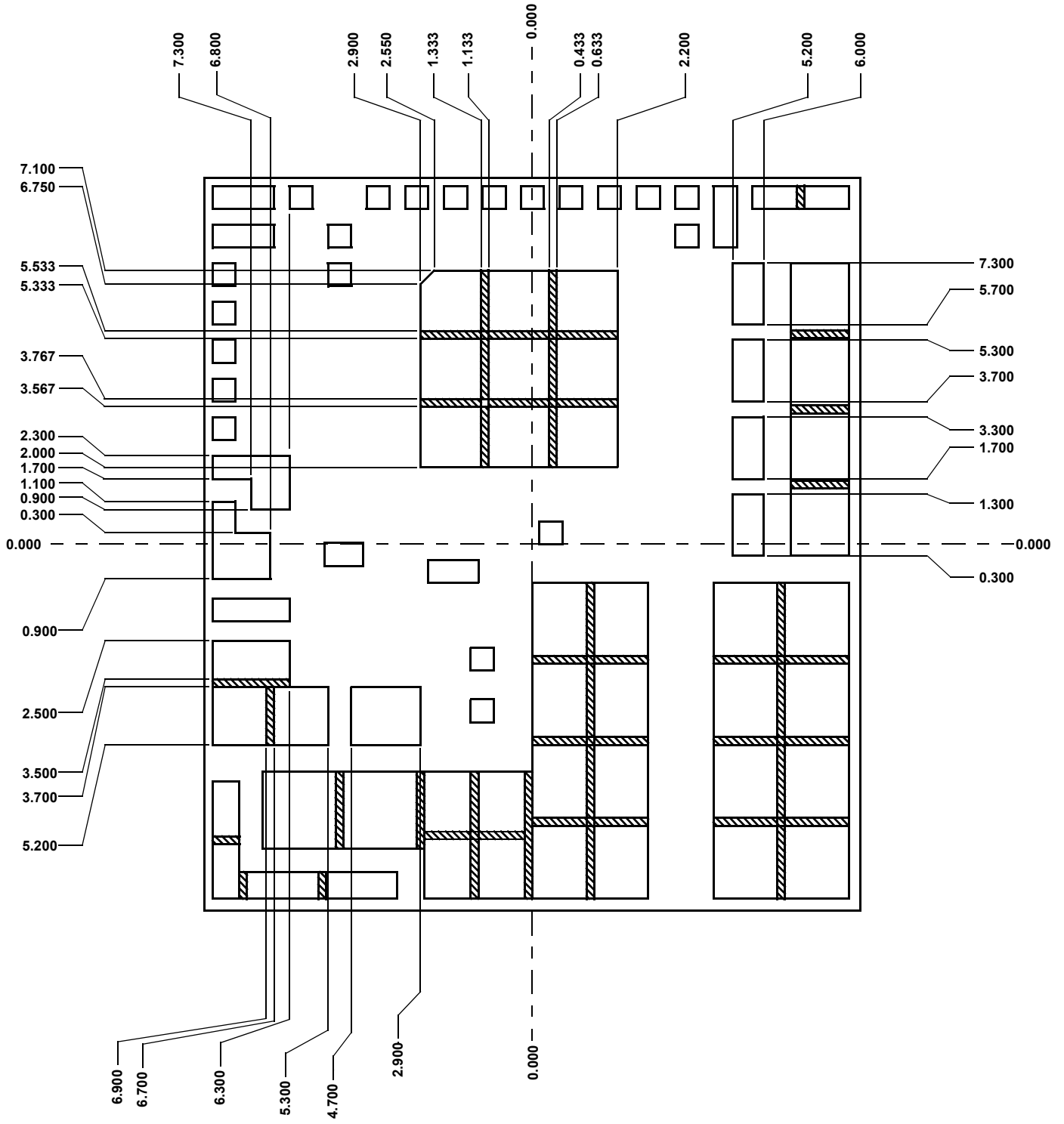


# Plastic Packages for Integrated Circuits



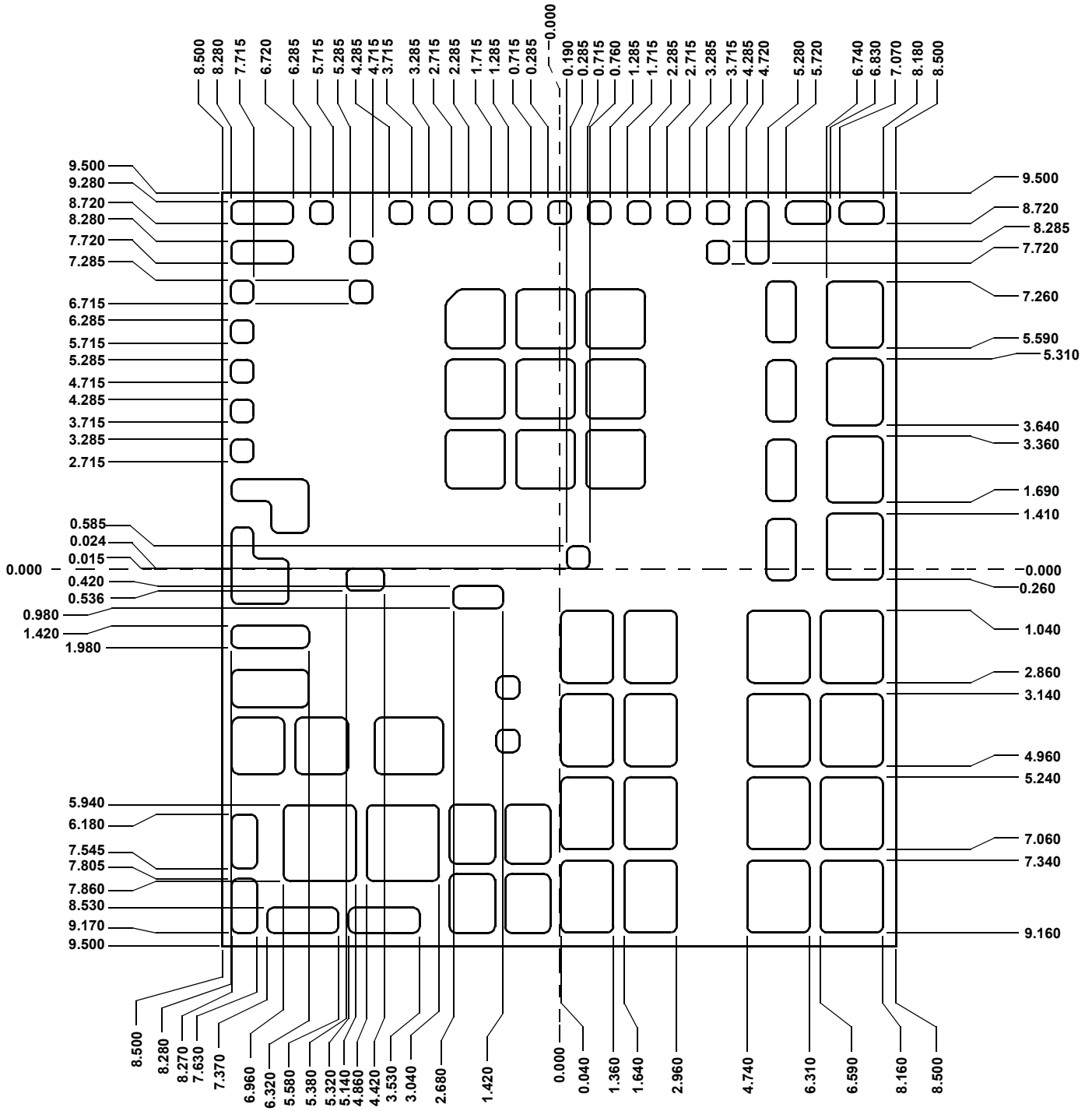
RECOMMENDED SOLDER MASK DEFINED PCB LAND PATTERN (1)  
TOP VIEW

# Plastic Packages for Integrated Circuits



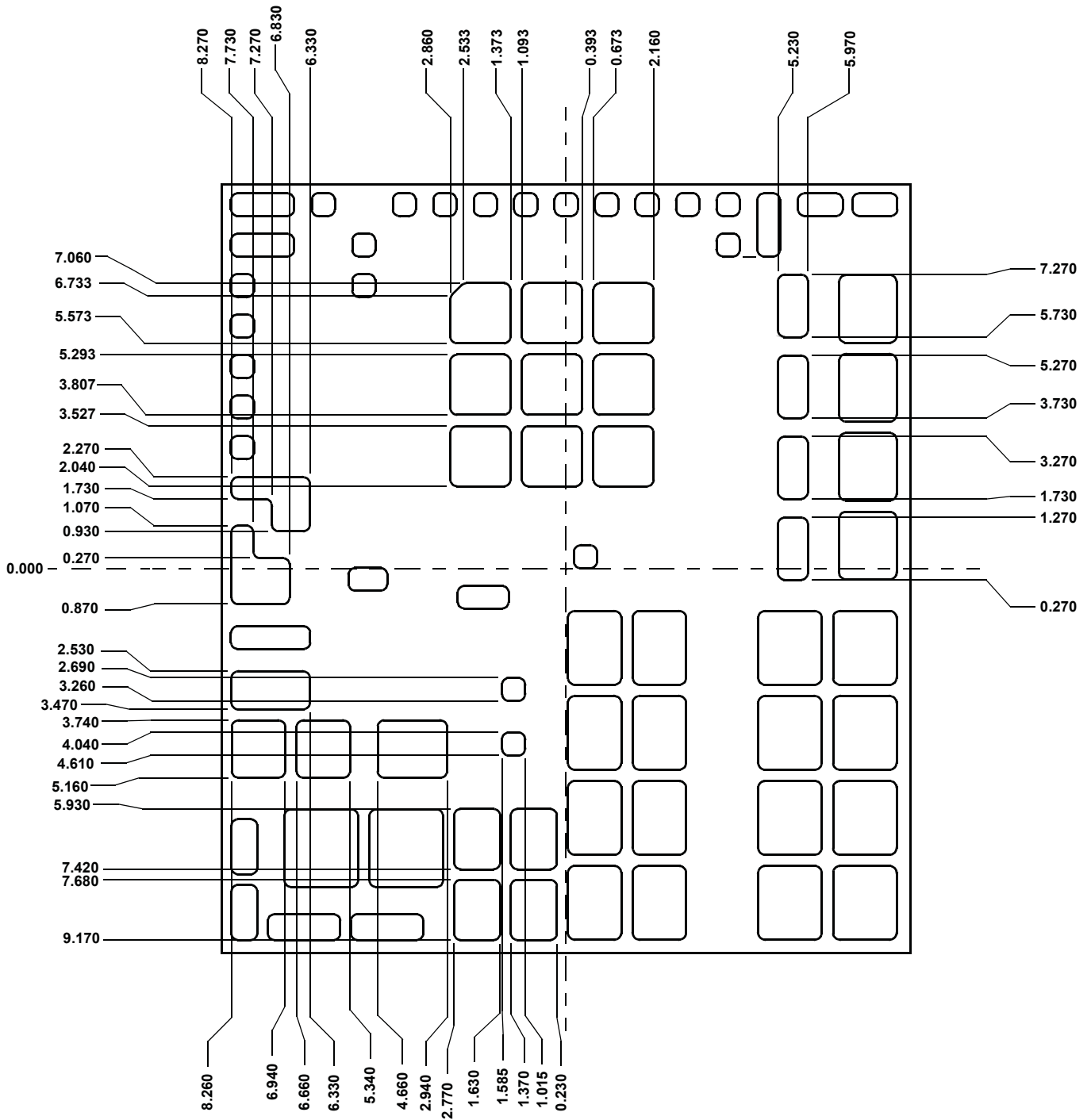
**RECOMMENDED SOLDER MASK DEFINED PCB LAND PATTERN (2)  
TOP VIEW**

# Plastic Packages for Integrated Circuits



**RECOMMENDED STENCIL PATTERN (90% PASTE TO PAD) (1)**  
**TOP VIEW**

# Plastic Packages for Integrated Circuits



**RECOMMENDED STENCIL PATTERN (90% PASTE TO PAD) (2)**  
**TOP VIEW**